

Department of Electronics and Telecommunication Engg.

Lecture Plan for EC 25XXX, B.Tech. II year

ELECTRONIC DEVICES

Session: June – Dec' 2024

Lecture No.	Topic Covered	Remark
1.	Unit1: Introduction to semiconductor Physics, Bohr's atomic structure,	
2.	E-K diagrams, Periodic Lattice, energy bands in Intrinsic and Extrinsic semiconductor, equilibrium carrier concentration	
3.	Direct and indirect band-gap semiconductors carrier transport, drift and diffusion current, mobility and resistivity	
4.	Generation & recombination of carrier, Poisson & continuity equation	
5.	Transient and diffusion capacitances, Switching time, Hall effect	
6.	Unit 2. Small signal switching model of P-N junction diode, Avalanche and Zener breakdown	
7.	Zener diode application as a voltage regulator	
8.	PN junction diode circuits and applications: clipper	
9.	Clamper and voltage multipliers	
10.	Rectifiers, construction, working, characteristics and applications: LED, photodiode	
11.	construction, working, characteristics and applications: tunnel diode	
12.	Schottky diode, Solar cell, thermistors	
13.	Unit 3. Charge transport in BJT, Minority carrier distribution and terminal currents	
14.	Base width modulation, Ebers Moll model	
15.	I-V characteristics for CB, CE and CC configurations, concept of loadline	
16.	Transistor Biasing circuit design: Fixed biased configuration, Emitter-bias configuration, Voltage divider bias configuration, collector feedback configuration, Emitter follower configuration	
17.	Stability concepts. Thermal runaway	
18.	Transistor based regulated power supply design	
19.	Unit 4. Construction & characteristics of p-channel, n-channel FET/JFET	
20.	Constructions, characteristics of Depletion type MOSFET, MOS Capacitance	
21.	Constructions, characteristics of Enhancement type MOSFET	
22.	CMOS: constructions, characteristics and applications	
23.	Source follower, common-gate. Channel length modulation	
24.	JFET Biasing: Fixed-bias, Self-bias, voltage divider	
25.	Unit 5. Concepts of Integrated circuits and their fabrications	
26.	Introduction of Surface mount devices (SMDs)	
27.	Silicon controlled rectifiers: construction, operation, characteristics	
28.	SCR applications; DIAC: construction, operation, characteristics	
29.	TRIAC, UJT: construction, operation, characteristics	
30.	Construction, operation, characteristics of Phototransistor; Opto-isolator	
31.	Seven segments- common anode, common cathode and Liquid Crystal Displays.	